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Kulicke & Soffa to Participate at SEMICON West 2017

SINGAPORE--(BUSINESS WIRE)-- Kulicke & Soffa Industries, Inc. (NASDAQ: KLIC) ("Kulicke & Soffa", "K&S" or the "Company"), announced today that it will be exhibiting at the SEMICON West trade show in San Francisco, California, from July 11 through July 13, 2017.

Kulicke & Soffa will be introducing, a video illustration of its first lithography solution developed specifically for Advanced Packaging. Additionally, K&S will be featuring several of its leading packaging solutions at booth number 5862 of the SEMICON West trade show.

- 1 **Asterion™ EV** - is built on an extended architecture of large frame for applications such as battery interconnect wire bonding, dual lane material handling systems and large power modules coupled with a compelling configurable bond head. It also supports a multitude of interconnect applications for both aluminum wire and *PowerRibbon™*.
- 1 **IConn^{PS} ProCu PLUS™** - is engineered to handle challenging copper bonding requirement. The ProCu5 process offers the highest level of copper process capability with many added controls and improvements, enabling robust wire bonding production for advanced node wafers down to 28 nanometer or below.
- 1 **Hybrid Wafer Feeder** - an innovative solution that enables the combination of ultra-high-speed passive and high-accuracy flip-chip bonding directly from wafer, tape-and-reel or wafer pack. It is ideal for high-volume System-in-Package (SiP), flip-chip, die-attach and wafer-level-packaging manufacturing with placement accuracy up to 7µm @ 3 sigma.

"We are excited to share with customers our first step-and-repeat lithography solution serving the broad-ranging requirements of the Advanced Packaging market. The high-throughput, modular i-line steppers uniquely utilize a laser-light source, driving best-in-class cost-of-ownership," said Gerrit van der Beek, Kulicke & Soffa's Vice President of Lithography Business Lines.

About Kulicke & Soffa

Kulicke & Soffa (NASDAQ: KLIC) is a leading provider of semiconductor packaging and electronic assembly solutions supporting the global automotive, consumer, communications, computing and industrial segments. As a pioneer in the semiconductor space, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions and organic development, adding advanced packaging, electronics assembly, wedge bonding and a broader range of expendable tools to its core offerings. Combined with its extensive expertise in process technology and focus on development, K&S is well positioned to help customers meet the challenges of packaging and assembling the next-generation of electronic devices. (www.kns.com)

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